



## Material Content Data Sheet



<b>Sales Product Name</b>		IPS65R1K4C6		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001722082						
<b>Package</b>		PG-TO251-3-344		<b>Weight*</b>		334.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.898	0.57	0.57	5672	5672
leadframe	inorganic material	phosphorus	7723-14-0	0.046	0.01		138	
	non noble metal	iron	7439-89-6	0.154	0.05		461	
	non noble metal	copper	7440-50-8	154.154	46.07	46.13	460804	461403
	non noble metal	aluminium	7429-90-5	0.473	0.14	0.14	1413	1413
wire	non noble metal	aluminium	7429-90-5	0.473	0.14	0.14	1413	1413
encapsulation	organic material	carbon black	1333-86-4	0.444	0.13		1328	
	plastics	epoxy resin	-	13.474	4.03		40278	
	inorganic material	silicondioxide	60676-86-0	134.150	40.10	44.26	401009	442615
leadfinish	non noble metal	tin	7440-31-5	4.142	1.24	1.24	12382	12382
plating	non noble metal	nickel	7440-02-0	0.607	0.18	0.18	1814	1814
solder	non noble metal	tin	7440-31-5	0.042	0.01		125	
	noble metal	silver	7440-22-4	0.052	0.02		156	
	non noble metal	lead	7439-92-1	1.999	0.60	0.63	5976	6257
heatspreader	inorganic material	phosphorus	7723-14-0	0.007	0.00		21	
	non noble metal	iron	7439-89-6	0.023	0.01		68	
	non noble metal	copper	7440-50-8	22.867	6.84	6.85	68355	68444
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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